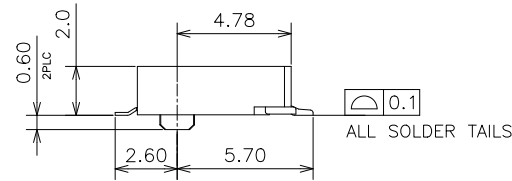
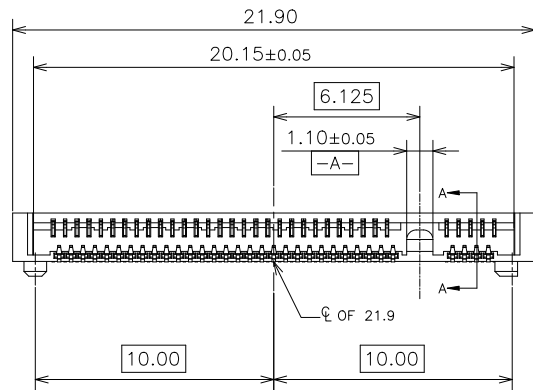
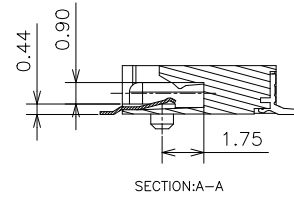
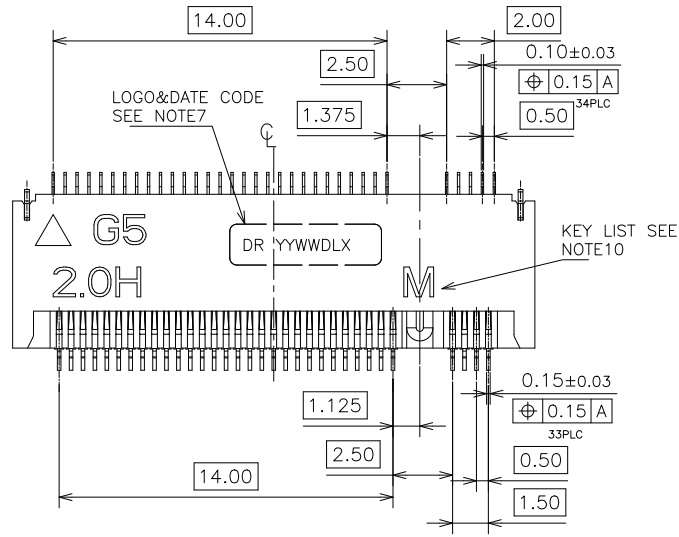


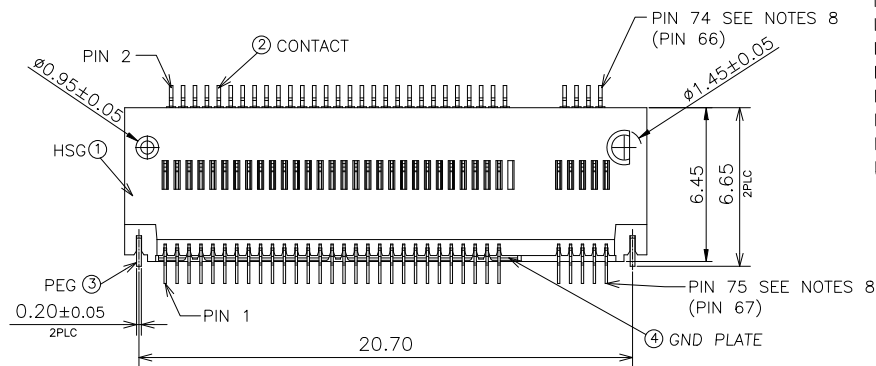
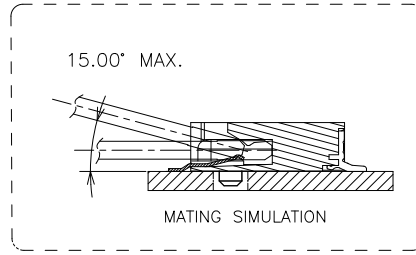
# HF

Halogen Free

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
X1			INITIAL RELEASE	11/29,23	Xin Lin
X2			UPDATE DRAWING	03/08,24	Xin Lin



- NOTES:
- PRODUCT MUST MEET CONTROLLED SUBSTANCES SPEC. ROHS 2.0
- MATERIAL:
    - HOUSING: LCP , UL94V-0; COLOR: BLACK
    - CONTACTS: COPPER ALLOY
    - PEG: STAINLESS STEEL
    - GND PLATE: STAINLESS STEEL
  - FINISH:
    - CONTACT:
      - 50u" MIN NICKEL UNDERPLATED ALL OVER,
      - Au GF PLATING ON SOLDERTAIL. GOLD PLATING (THICKNESS SEE NOTE 10) ON CONTACT AREA.
    - PEG:
      - 100u" MIN. MATTE-TIN. 50u"MIN. NICKEL UNDERPLATING.
  - REFLOW SOLDER CAPABLE TO 260°C 10SEC.
  - ELECTRICAL CHARACTERISTICS:
    - CONTACT CURRENT RATING: 0.5 AMPERE MAX, PER PIN,
    - VOLTAGE RATING: 50V AC.
    - INSULATION RESISTANCE: 500M OHM MIN.(INITIAL), 100M OHM MIN.(FINAL), AT 500V DC, FOR 1 MINUTE.
    - DIELECTRIC WITHSTANDING VOLTAGE: 300V AC RMS AT 60HZ, FOR 1 MINUTE.
    - CONTACT RESISTANCE: 55m OHM MAX(INITIAL) ΔR 20m OHM MAX(FINAL)
  - OPERATION TEMPERATURE: -40°C TO +85°C
  - MATING FORCE: 2.04Kgf MAX.  
DURABILITY: 25 CYCLES;60 CYCLES(GOLD PLATING 30u" ON CONTACT AREA).
  - DATE CODE: YYWDLX  
 YY: YEAR (09: 2009)  
 WW: WEEK (25: THE 25TH WEEK)  
 D: DAY (1~7: SUNDAY~SATURDAY)  
 L: LINE NUMBER OF ASSEMBLY (A: LINE A)  
 X: MANUFACTURE CODE
  - CONNECTOR ACTUAL PIN QUANTITY IS 67,AS THE KEY TAKING OUT 8 PINS.
  - RECOMMENDED STENCIL THICKNESS 0.12MM MIN
  - PART NUMBER DESCRIPTION:  
 5621D3-012 H \* B \* R  
 H=HALOGEN FREE  
 R=EMBOSS WIDTH 44mm, SLOT BACKWARD  
 LOGO:  
 0=NO LOGO  
 1=DR LOGO  
 KEY TYPE:  
 B=KEY M  
 PLATING CODE:  
 1=Au1u"                      2=Au5u"  
 3=Au10u"                     4=Au15u"  
 5=Au30u"                     6=Au20u"  
 HALOGEN CODE:  
 H=HALOGEN FREE



DIM	TOL	DIM	TOL
X.	±0.30	X.	±2*
.X	±0.25	.X	±1*
.XX	±0.20		



**DEREN**  
SHENZHEN DEREN ELECTRONIC CO., LTD

C-DWG:	TY	DATE	TITLE:M.2 GEN5 2.0H KEY M 0.5A
DESIGN:	Xin Lin	03/08,24	P/N:5621D3-012H-*B*R
CHECK:	Mike Chen	03/08,24	SHEET: 1/3
APPROVAL:	Bill Lin	03/08,24	SCALE: N/A UNIT: mm

DRAW NO.
SC2309671-1

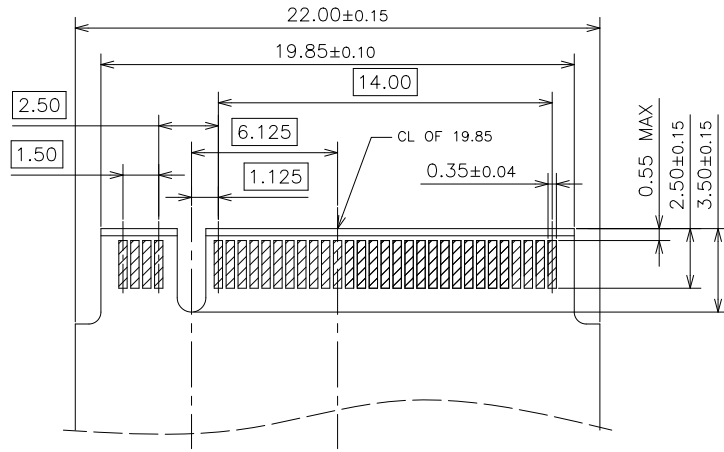
REV.	X2

# HF

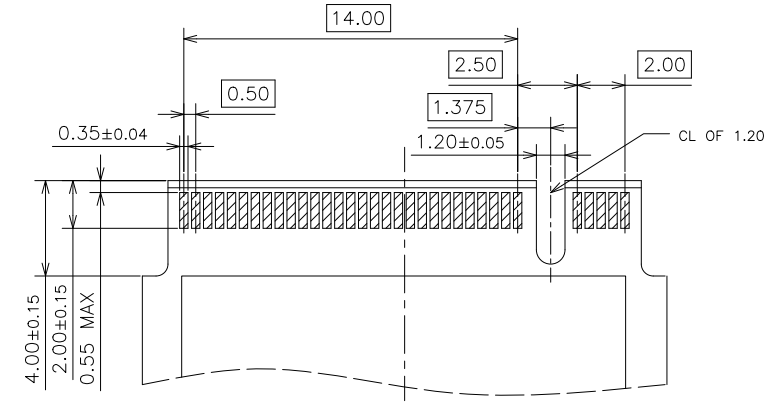
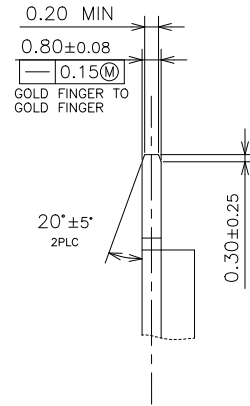
Halogen Free

## PLUG PCB

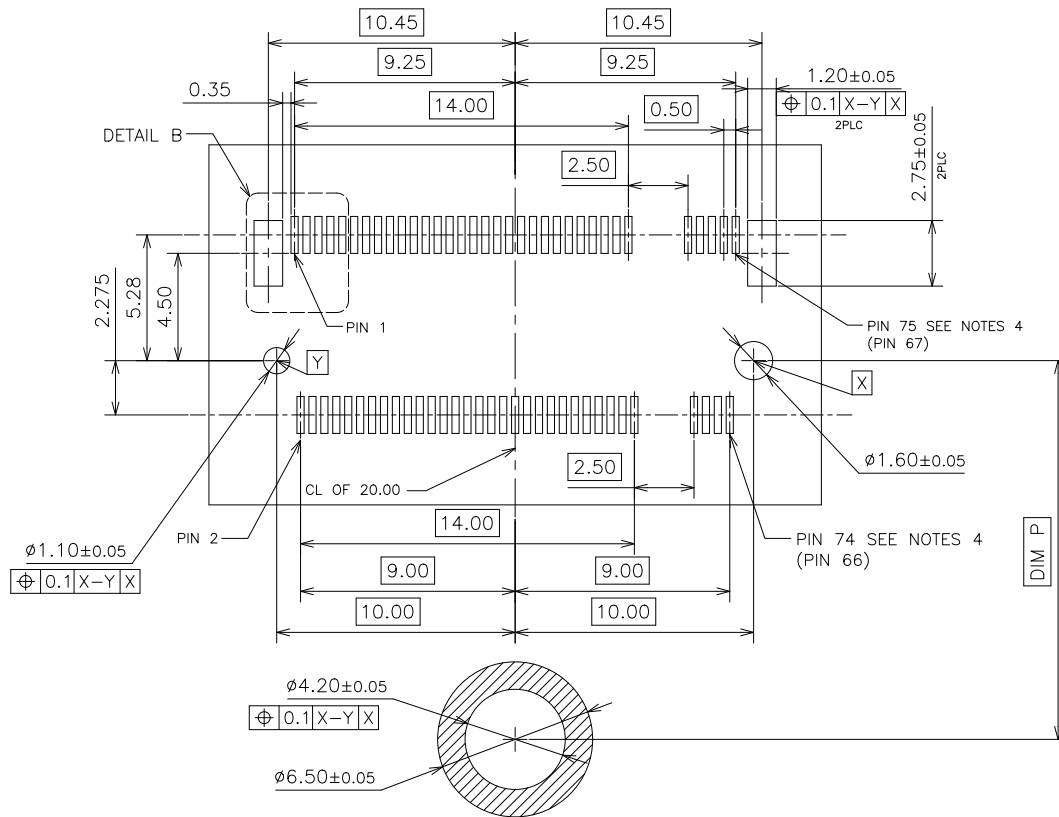
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
X1			INITIAL RELEASE	11/29,23	Xin Lin
X2			UPDATE DRAWING	03/08,24	Xin Lin



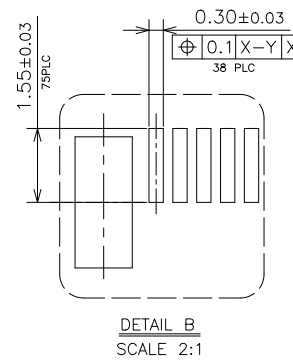
BOTTOM SIDE



TOP SIDE



RECOMMENDED PCB LAYOUT(TOP VIEW)



22110	108.25
2280	78.25
2260	58.25
2242	40.25
2230	28.25
3042	40.25
3030	28.25
MODULE TYPE	DIM P

DIM	TOL	DIM	TOL
X.	±0.30	X.	±2°
.X	±0.25	.X	±1°
.XX	±0.20		



**DEREN**

SHENZHEN DEREN ELECTRONIC CO., LTD

DRAW NO.  
SC2309671-1

C-DWG:	TY	DATE
DESIGN:	Xin Lin	03/08,24
CHECK:	Mike Chen	03/08,24
APPROVAL:	Bill Lin	03/08,24

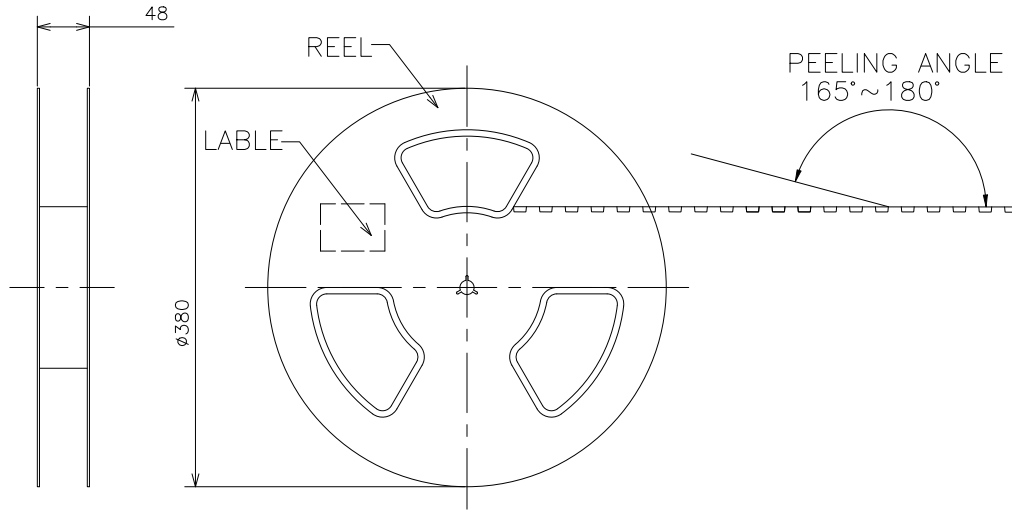
TITLE:M.2 GEN5 2.0H KEY M 0.5A		
P/N:5621D3-012H-*B*R		
SHEET:	2/3	
SCALE:	N/A	UNIT: mm

REV. X1

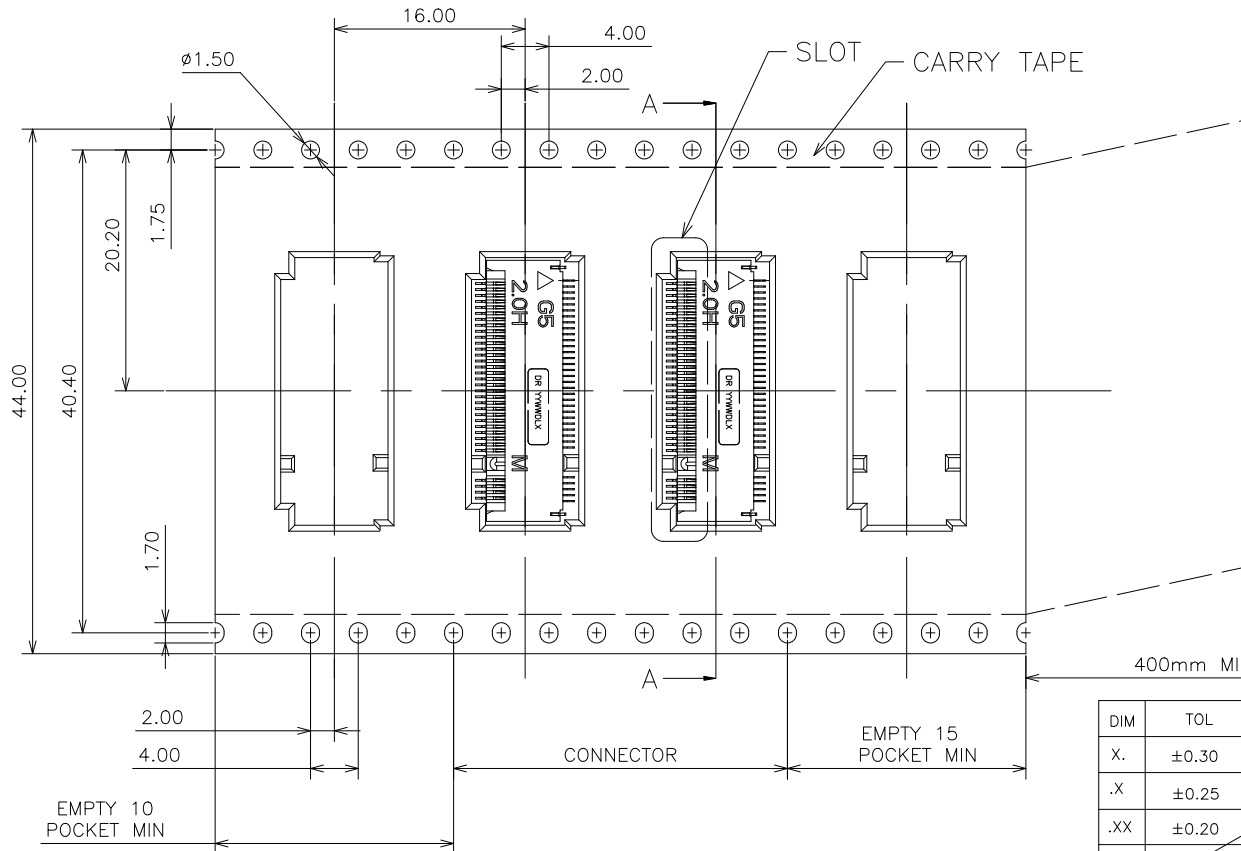
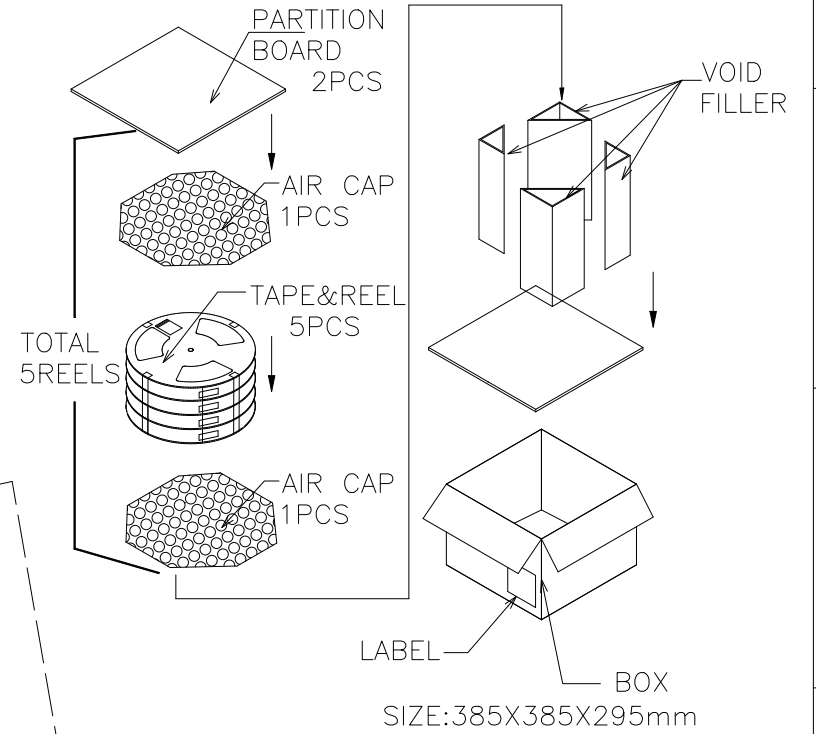
# HF

Halogen Free

FEEDING DIRECTION →



REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
X1			INITIAL RELEASE	11/29,23	Xin Lin
X2			UPDATE DRAWING	03/08,24	Xin Lin



1500	5	7500	X.XXKg	X.XXKg
PCS/TAPE	REELS/BOX	PCS/BOX	GROSS WEIGHT	NET WEIGHT

DIM	TOL	DIM	TOL
X.	±0.30	X.	±2'
.X	±0.25	.X	±1'
.XX	±0.20		

**DEREN**  
SHENZHEN DEREN ELECTRONIC CO., LTD

C-DWG:	TY	DATE	TITLE:M.2 GEN5 2.0H KEY M 0.5A
DESIGN:	Xin Lin	03/08,24	P/N:5621D3-012H-*B*R
CHECK:	Mike Chen	03/08,24	SHEET: 3/3
APPROVAL:	Bill Lin	03/08,24	SCALE: N/A UNIT: mm

DRAW NO. SC2309671-1

REV. X1